





A     NOTE: 3       A     NOTES:       1. DIWENSIONS AND TO FRANCES ARE IN ACCORDANCE WITH ARMITY 4,504, 1984 UNLESS OTHERNISE SPECIFIED.       CONNECTOR NOTES:       (2)       (3)       0        0       0 <td></td>	
<ul> <li>I. DIMENSIONS AND TOLEFANCES ARE IN ACCORDANCE WITH ASAME TIA. W. 1994 UNLISS OTHERWISE SPECIFIED.</li> <li>CONNECTOR NOTES:</li> <li>(a) HOUSING MATERIAL: UL 94 V-0 GLASS FILLED HIGH-TEMP THERMOPLASTIC POORE CONTACT MATERIAL: COPPER ALLOY SIGNAL PIN MATERIAL: COPPER ALLOY</li> <li>3. SEE ITEM I &amp; 2 IN PRINT HOSAIBS FOR PLATING SPEC OF S1939-629 AND S1939-629 F RESPECTIVELY.</li> <li>(b) MANUFACTURET'S NAME, DATE COME AND OPTIONAL PIN TO APPEAR ON THIS SUBFACE. THE PIN CAN BE OMITTED IF THERE IS NOT ENOUGH SPACE ON THIS SUBFACE. THE PIN CAN BE OMITTED IF THERE IS NOT ENOUGH SPACE OF THIS SUBFACE. THE PIN CAN BE OMITTED IF THERE IS NOT ENOUGH SPACE ON THIS SUBFACE. THE PIN CAN BE OMITTED IF THERE IS NOT ENOUGH SPACE OF SIDSING.</li> <li>(c) MANUFACTURET'S NAME. PART ECONTAL PIN TO APPEAR ON THIS SUBFACE IN THATS.</li> <li>PCB NOILS:</li> <li>(c) ACLAGED IN TRATS.</li> <li>PCB NOILS:</li> <li>(c) MOUNTING HOLES, WHERE APPLICABLE, ARE UNPLATED.</li> <li>(f) WOUNTING HOLES, WHERE APPLICABLE, ARE UNPLATED.</li> <li>(g) Ø1.1SIAD 025 DEFLICED HOLES SIZE.</li> <li>(g) Ø1.1SIAD 025 DEFLICED HOLES SIZE.</li> <li>(g) Ø1.1SIAD 025 DEFLICED HILES PLATED WITH QUESTION CONTENT OF ACTIVE OF SIGNAL PLATED.</li> <li>(g) Ø1.1SIAD 025 DEFLICED HILE DUESTATED WITH QUESTION CONTENT OF ACTIVE OF ALLOY OF PLATED.</li> <li>(g) Ø1.1SIAD 025 DEFLICED HILES PLATED WITH QUESTION CONTENT OF ACTIVE OF ALLOY OF ALL</li></ul>	
B          1. DIVENSIONS AND TOLEFANCES ARE IN ACCORDANCE WITH ASSE TIES:         CONNECTOR NOTES:         (2) HOUSING MATERIAL: UL 94 Y-0 GLASS FILLED HIGH-TEMP THERMOPLASTIC POWER CONTACT MATERIAL: OCPTER ALLOY SIGNAL PIN MATERIAL: COPPER ALLOY SIGNAL PIN MATERIAL: COPPER ALLOY SIGNAL PIN MATERIAL: COPPER ALLOY SIGNAL PIN MATERIAL: DOPER ALLOY SIGNAL PIN MATERIAL: DOPERATION SIGNAL PIN MATERIAL: DOPERATION SIGNAL PIN HITHOUSE SIGNAL PIN MATERIAL: DOPERATION SIGNAL PIN HOUSE PLATED WITH SIGNAL PIN MATERIAL: DO ACHIEVE SIGNAL PIN MATERIAL: DO ACHIEVE SIGNAL PIN MATERIAL: DO ACHIEVE SIGNAL PIN MATERIAL: DOPERATION SIGNAL PIN HE CUSTOMER. SIGNAL PIN MATERIAL: DOPERATION SIGNAL PIN HITHOUSE PIN MATERIAL: DOPERATION DATERIAL: SIGNAL PIN MATERIAL: DOPERATION SIGNAL PIN HITHOUSE ACHIEVE SIGNAL PIN MATERIAL: DOPERATION SIGNAL PI	A
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POWER CONTACT MATERIAL: COPPER ALLOY SIGNAL FIN MATERIAL: COPPER ALLOY       3. SEE ITEM I & 2 IN PRINT 10064183 FOR PLATING SPEC OF 51939-629 AND 51939-629LF RESPECTIVELY.       (4) MANUFACTURER'S NAME, DATE CODE AND OPTIONAL P/N TO APPEAR ON THIS SURFACE. THE P/N CAN BE OWITTED IF THERE IS NOT ENOUGH SPACE ON THIS SURFACE.       5. PRODUCT SPECIFICATION 65-12-149. APPLICATION SPECIFICATION BUS-20-067.       6. PACKAGED IN TRAYS.       PCB NOTES:       7. ALL HOLE DIAMETERS ARE FINISHED HOLE SIZE.       (8) MOUNTING HOLES, WHERE APPLICABLE, ARE UNPLATED.       (9) Ø1.151±0.025 DRILLED HOLES PLATED NITH 0.008 MIN SAPE OR SA OVER 0.03 10 0.05 CO FULTING TO ACHIEVE Ø1.02±0.07 HOLE.       (10) "DIM XXX" TO BE DETERMINED BY THE CUSTOMER.       (11) CONNECTOR KEEP-OUT ZONE.	
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